3.3V ECL +2 Divider

Description

The MC100LVEL32 is an integrated ÷2 divider. The LVEL32 is functionally identical to the EL32, but operates from a 3.3 V supply.

The reset pin is asynchronous and is asserted on the rising edge. Upon power-up, the internal flip-flop will attain a random state; the reset allows for the synchronization of multiple LVEL32's in a system.

The V_{BB} pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to V_{BB} as a switching reference voltage. V_{BB} may also rebias AC coupled inputs. When used, decouple V_{BB} and V_{CC} via a $0.01~\mu F$ capacitor and limit current sourcing or sinking to 0.5~mA. When not used, V_{BB} should be left open.

Features

- 510 ps Propagation Delay
- 2.6 GHz Typical Maximum Frequency
- ESD Protection: Human Body Model; >4 kV, Machine Model; >200 V
- The 100 Series Contains Temperature Compensation
- PECL Mode Operating Range:
 V_{CC} = 3.0 V to 3.8 V with V_{EE} = 0 V
- NECL Mode Operating Range: V_{CC} = 0 V with V_{EE} = -3.0 V to -3.8 V
- Internal Input Pulldown Resistors
- Meets or Exceeds JEDEC Spec EIA/JESD78 IC Latchup Test
- Moisture Sensitivity Level 1
 For Additional Information, see Application Note AND8003/D
- Flammability Rating: UL 94 V-0 @ 0.125 in, Oxygen Index: 28 to 34
- Transistor Count = 111 devices
- Pb-Free Packages are Available



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MARKING DIAGRAMS*



SOIC-8 D SUFFIX CASE 751





TSSOP-8 DT SUFFIX CASE 948R







DFN8 MN SUFFIX CASE 506AA

A = Assembly Location

L = Wafer Lot

Y = Year

W = Work Week

 \overline{M} = Date Code

= Pb-Free Package

(Note: Microdot may be in either location)
*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

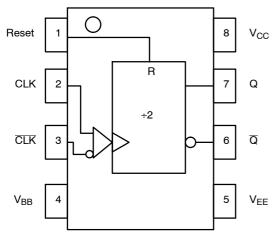


Figure 1. Logic Diagram and Pinout Assessment

Table 1. PIN DESCRIPTION

Pin	Function
CLK*, CLK**	ECL Differential Clock Inputs
Q, \overline{Q}	ECL Differential Data ÷2 Outputs
Reset*	ECL Asynch Reset
V_{BB}	Reference Voltage Output
V _{CC}	Positive Supply
V _{EE}	Negative Supply
EP	(DFN8 only) Thermal exposed pad must be connected to a sufficient thermal conduit. Electrically connect to the most negative supply (GND) or leave unconnected, floating open.

^{*}Pin will default low when left open, per internal 75 K pull-down to

Table 2. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V _{CC}	PECL Mode Power Supply	V _{EE} = 0 V		8 to 0	V
V _{EE}	NECL Mode Power Supply	V _{CC} = 0 V		-8 to 0	V
VI	PECL Mode Input Voltage NECL Mode Input Voltage	V _{EE} = 0 V V _{CC} = 0 V	$V_{I} \leq V_{CC}$ $V_{I} \geq V_{EE}$	6 to 0 -6 to 0	V V
VI	PECL Mode Input Voltage NECL Mode Input Voltage	V _{EE} = 0 V V _{CC} = 0 V	$V_{I} \le V_{CC}$ $V_{I} \ge V_{EE}$	6 to 0 -6 to 0	V V
l _{out}	Output Current	Continuous Surge		50 100	mA mA
I _{BB}	V _{BB} Sink/Source			± 0.5	mA
T _A	Operating Temperature Range			-40 to +85	°C
T _{stg}	Storage Temperature Range			-65 to +150	°C
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SOIC-8 SOIC-8	190 130	°C/W
θ _{JC}	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC-8	41 to 44 ± 5%	°C/W
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-8 TSSOP-8	185 140	°C/W °C/W
θJC	Thermal Resistance (Junction-to-Case)	Standard Board	TSSOP-8	41 to 44 ± 5%	°C/W
θ_{JA}	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	DFN8 DFN8	129 84	°C/W °C/W
T _{sol}	Wave Solder Pb Pb-Free	<2 to 3 sec @ 248°C <2 to 3 sec @ 260°C		265 265	°C
θЈС	Thermal Resistance (Junction-to-Case)	(Note 1)	DFN8	35 to 40	°C/W

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

 V_{EE} .

** Pin will default to $V_{CC}/2$ when left open per internal 75 KΩ pull-down to V_{EE} and 75 KΩ pull-up to V_{CC} .

JEDEC standard multilayer board – 2S2P (2 signal, 2 power)

Table 3. LVPECL DC CHARACTERISTICS $V_{CC} = 3.3 \text{ V}$; $V_{EE} = 0.0 \text{ V}$ (Note 1)

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current		29	35		29	35		31	36	mA
V _{OH}	Output HIGH Voltage (Note 3)	2215	2295	2420	2275	2345	2420	2275	2345	2420	mV
V _{OL}	Output LOW Voltage (Note 3)	1470	1605	1745	1490	1595	1680	1490	1595	1680	mV
V _{IH}	Input HIGH Voltage (Single-Ended)	2135		2420	2135		2420	2135		2420	mV
V _{IL}	Input LOW Voltage (Single-Ended)	1490		1825	1490		1825	1490		1825	mV
V _{BB}	Output Voltage Reference	1.92		2.04	1.92		2.04	1.92		2.04	V
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 7) $V_{PP} < 500 \text{ mV} \\ V_{PP} \geqq 500 \text{ mV}$	1.2 1.4		3.1 3.1	1.1 1.3		3.1 3.1	1.1 1.3		3.1 3.1	V V
I _{IH}	Input HIGH Current			150			150			150	μΑ
I _{IL}	Input LOW Current CLK CLK	0.5 -600			0.5 -600			0.5 -600			μ Α μ Α

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 2. Input and output parameters vary 1:1 with $V_{CC}.\ V_{EE}$ can vary $\pm 0.3\ V.$
- 3. Outputs are terminated through a 50 Ω resistor to VCC 2.0 V.

Table 4. LVNECL DC CHARACTERISTICS $V_{CC} = 0.0 \text{ V}$; $V_{EE} = -3.3 \text{ V}$ (Note 5)

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
I _{EE}	Power Supply Current		29	35		29	35		31	36	mA
V _{OH}	Output HIGH Voltage (Note 6)	-1085	-1005	-880	-1025	-955	-880	-1025	-955	-880	mV
V _{OL}	Output LOW Voltage (Note 6)	-1830	-1695	-1555	-1810	-1705	-1620	-1810	-1705	-1620	mV
V _{IH}	Input HIGH Voltage (Single-Ended)	-1165		-880	-1165		-880	-1165		-880	mV
V _{IL}	Input LOW Voltage (Single-Ended)	-1810		-1475	-1810		-1475	-1810		-1475	mV
V _{BB}	Output Voltage Reference	-1.38		-1.26	-1.38		-1.26	-1.38		-1.26	V
V _{IHCMR}	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 7) $V_{PP} < 500 \text{ mV}$ $V_{PP} \ge 500 \text{ mV}$	-2.1 -1.9		-0.2 -0.2	-2.1 -1.9		-0.2 -0.2	-2.1 -1.9		-0.2 -0.2	V
I _{IH}	Input HIGH Current			150			150			150	μΑ
I _{IL}	Input LOW Current CLK CLK	0.5 -600			0.5 -600			0.5 -600			μ Α μ Α

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 5. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary ± 0.3 V.
- 6. Outputs are terminated through a 50 Ω resistor to V_{CC} 2.0 V.
- V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal.
 Normal operation is obtained if the HIGH level falls within the specified range and the peak-to-peak voltage lies between V_{PP}min and 1 V.

^{4.} V_{IHCMR} min varies 1:1 with V_{EE}, max varies 1:1 with V_{CC}. The V_{IHCMR} range is referenced to the most positive side of the differential input signal. Normal operation is obtained if the HIGH level falls within the specified range and the peak-to-peak voltage lies between V_{PP}min and 1 V.

Table 5. AC CHARACTERISTICS $V_{CC} = 3.3 \text{ V}$; $V_{EE} = 0.0 \text{ V}$ or $V_{CC} = 0.0 \text{ V}$; $V_{EE} = -3.3 \text{ V}$ (Note 8)

			-40°C			25°C			85°C		
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f _{max}	Maximum Toggle Frequency	2.2	2.5		2.4	2.6		2.6	2.8		GHz
t _{PLH} t _{PHL}	Propagation Delay CLK to Q (Differential) CLK to Q (Single-Ended) Reset to Q	350 300 440	500 500 555	530 580 640	370 320 450	510 510 540	550 600 650	410 360 480	540 540 580	590 640 680	ps
t _{RR}	Reset Recovery	175	50		175	50		175	50		ps
t _{PW}	Minimum Pulse Width Reset	500	300		500	300		500	300		ps
t _{JITTER}	Random Clock Jitter (RMS)		2.0			2.0			2.0		ps
V _{PP}	Input Swing (Differential Swing) (Note 9)	150		1000	150		1000	150		1000	mV
t _r t _f	Output Rise/Fall Times Q (20% – 80%)	120	225	320	120	225	320	120	225	320	ps

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

- 8. V_{EE} can vary ±0.3 V.
- 9. VPP(min) is input swing measured single-ended on each input in differential configuration.

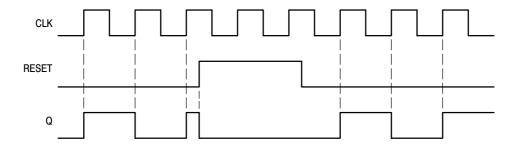


Figure 1. Timing Diagram

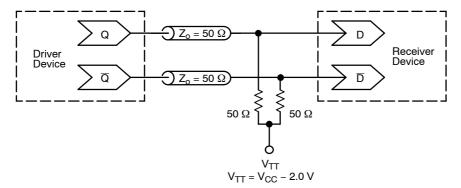


Figure 2. Typical Termination for Output Driver and Device Evaluation (See Application Note AND8020/D – Termination of ECL Logic Devices.)

ORDERING INFORMATION

Device	Package	Package [†]
MC100LVEL32D	SOIC-8	98 Units / Rail
MC100LVEL32DG	SOIC-8 (Pb-Free)	98 Units / Rail
MC100LVEL32DR2	SOIC-8	2500 / Tape & Reel
MC100LVEL32DR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel
MC100LVEL32DT	TSSOP-8	100 Units / Rail
MC100LVEL32DTG	TSSOP-8 (Pb-Free)	100 Units / Rail
MC100LVEL32DTR2	TSSOP-8	2500 / Tape & Reel
MC100LVEL32DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel
MC100LVEL32MNR4	DFN8	1000 / Tape & Reel
MC100LVEL32MNR4G	DFN8 (Pb-Free)	1000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Resource Reference of Application Notes

AN1405/D - ECL Clock Distribution Techniques

AN1406/D – Designing with PECL (ECL at +5.0 V)

AN1503/D - ECLinPS I/O SPiCE Modeling Kit

AN1504/D - Metastability and the ECLinPS Family

AN1568/D - Interfacing Between LVDS and ECL

AN1672/D - The ECL Translator Guide

AND8001/D - Odd Number Counters Design

AND8002/D - Marking and Date Codes

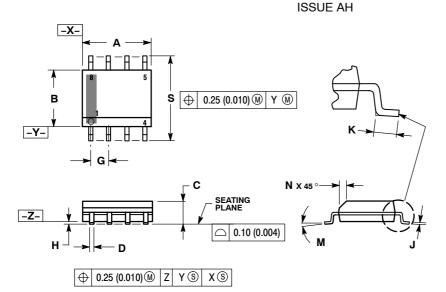
AND8020/D - Termination of ECL Logic Devices

AND8066/D - Interfacing with ECLinPS

AND8090/D - AC Characteristics of ECL Devices

PACKAGE DIMENSIONS

SOIC-8 NB CASE 751-07



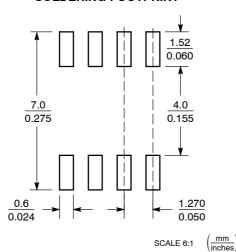
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER
- ANSI Y14.5M, 1982.
 CONTROLLING DIMENSION: MILLIMETER.
 DIMENSION A AND B DO NOT INCLUDE
 MOLD PROTRUSION.
- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
- PER SIDE.

 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

 6. 751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 751-07.

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.80	5.00	0.189	0.197
В	3.80	4.00	0.150	0.157
С	1.35	1.75	0.053	0.069
D	0.33	0.51	0.013	0.020
G	1.27	7 BSC	0.05	0 BSC
Н	0.10	0.25	0.004	0.010
J	0.19	0.25	0.007	0.010
K	0.40	1.27	0.016	0.050
M	0 °	8 °	0 °	8 °
N	0.25	0.50	0.010	0.020
S	5.80	6.20	0.228	0.244

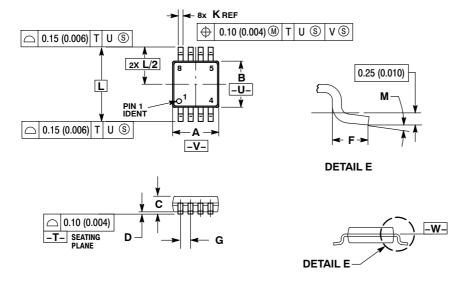
SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

PACKAGE DIMENSIONS

TSSOP-8 **DT SUFFIX** PLASTIC TSSOP PACKAGE CASE 948R-02 **ISSUE A**



NOTES:

- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

 2. CONTROLLING DIMENSION: MILLIMETER.

 3. DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.

 4. DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) PER SIDE.

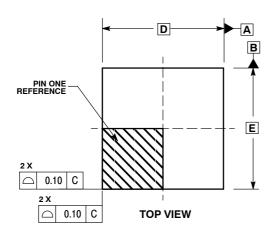
 5. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.

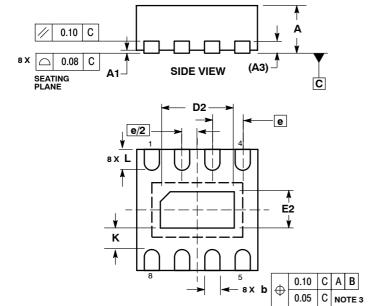
 6. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE —W.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	2.90	3.10	0.114	0.122	
В	2.90	3.10	0.114	0.122	
С	0.80	1.10	0.031	0.043	
D	0.05	0.15	0.002	0.006	
F	0.40	0.70	0.016	0.028	
G	0.65	BSC	0.026	BSC	
K	0.25	0.40	0.010	0.016	
L	4.90	BSC	0.193	BSC	
М	0°	6 °	0°	6°	

PACKAGE DIMENSIONS

DFN8 CASE 506AA-01 ISSUE D





NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994 .
- 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. DIMENSION b APPLIES TO PLATED
 TERMINAL AND IS MEASURED BETWEEN
- 0.25 AND 0.30 MM FROM TERMINAL. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS						
DIM	MIN	MAX					
Α	0.80	1.00					
A1	0.00	0.05					
А3	0.20	REF					
b	0.20	0.30					
D	2.00	BSC					
D2	1.10	1.30					
Е	2.00	BSC					
E2	0.70	0.90					
е	0.50	0.50 BSC					
K	0.20						
Ь	0.25	0.35					

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